



Recommended Mating Board Footprint
(Tolerance ±0.05)

Material and Plating:

Housing: LCP, UL94V-0, Black.
Signal Contacts : Nickel Copper.
30u" Gold Plated on Contact Area and 80u" Min Tin Plated on Solder Tail over Nickel 50u" Min .

Electrical Characteristics:

Current Rating: 3.1A .
Dielectric Withstanding Voltage: AC 600V For 1 minute.
Insulator Resistance: 6000MΩ min. at DC 250V.
Contact Resistance: 8.4mΩ max. at DC 100mA.
Operating Temperature: -55°C~+125°C.

***RoHS Compliant**

Speed: 28+Gbps @-3dB.

<p>RoHS Compliant</p>		<p>HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.</p>	
		<p>PART NAME 品名 0.8mm High Speed Card Edge Connector 2X10Pin SMT 90° Type Material:LCP With Plastic Posts Without Front Key Selective Gold 30U" Plating Black Color ROHS</p>	
<p>APPD. 核准</p>	<p>SCALE 比例 參考</p>	<p>Tolerances x = ±0.50 .x = ±0.25 .xx = ±0.15</p>	<p>PART NO. 料號 C3552-20PNINXBR</p>
<p>DWG. 製圖 Betty</p>	<p>UNIT 單位 M M</p>	<p>SIZE. 紙張尺寸 A 4</p>	
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